



PD54003L-E

RF power transistor, LdmoST plastic family
N-channel enhancement-mode, lateral MOSFETs

Features

- Excellent thermal stability
- Common source configuration
- $P_{OUT} = 3\text{ W}$ with 20dB gain@500 MHz
- New leadless plastic package
- ESD protection
- Supplied in tape and reel of 3 K units
- In compliance with 2002/95/EC european directive

Description

The PD54003L-E is a common source N-channel, enhancement-mode lateral field-effect RF power transistor. It is designed for high gain, broadband commercial and industrial application. It operates at 7 V in common source mode at frequencies of up to 1 GHz. PD54003L-E boasts the excellent gain, linearity and reliability of STH1LV latest LDMOS technology mounted in the innovative leadless SMD plastic package, PowerFLAT™.

PD54003L-E's superior linearity performances makes it an ideal solution for car mobile radio.

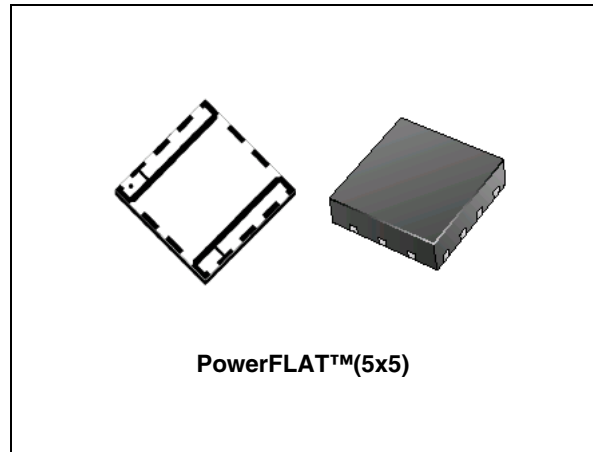


Figure 1. Pin configuration

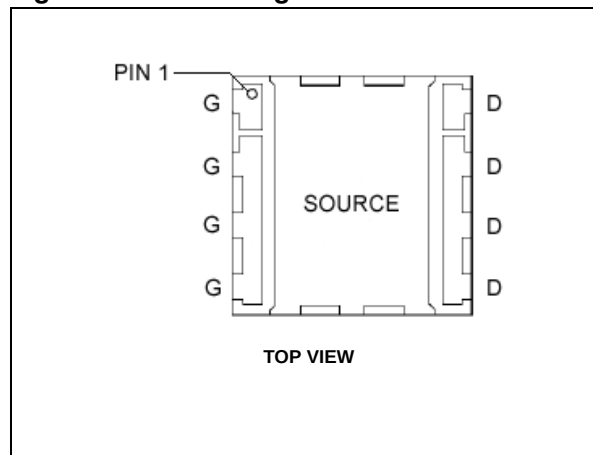


Table 1. Device summary

Order code	Marking	Package	Packaging
PD54003L-E	54003	PowerFLAT™(5x5)	Tape and reel

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1 Maximum ratings

($T_{CASE}=25^{\circ}\text{C}$)

Table 2. Absolute maximum ratings ($T_{CASE}=25^{\circ}\text{C}$)

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-source voltage	25	V
V_{GS}	Gate-source voltage	-0.5 to +15	V
I_D	Drain current	4	A
P_{DISS}	Power dissipation (@ $T_C = 70^{\circ}\text{C}$)	19.5	W
T_{stg}	Storage temperature	- 65 to +150	$^{\circ}\text{C}$
T_j	Operating junction temperature	150	$^{\circ}\text{C}$

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction-case thermal resistance	4.1	$^{\circ}\text{C/W}$

2 Electrical specification

($T_{CASE}=25^{\circ}\text{C}$)

Table 4. Static

Symbol	Test conditions	Min.	Typ.	Max.	Unit
I_{DSS}	$V_{GS}=0\text{V}$, $V_{DS}=25\text{V}$			1	μA
I_{GSS}	$V_{GS}=5\text{V}$, $V_{DS}=0\text{V}$			1	μA
$V_{GS(Q)}$	$V_{DS}=10\text{V}$, $I_D=50\text{mA}$	2.0		3.3	V
$V_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=0.5\text{A}$		0.13	0.16	V
g_{fs}	$V_{DS}=10\text{V}$, $I_D=3.2\text{A}$		TBD		mho
C_{iss} C_{oss} C_{rss}	$V_{GS}=0\text{V}$, $V_{DS}=7.5\text{V}$, $f=1\text{MHz}$		54 43 4		pF pF pF

Table 5. Dynamic

Symbol	Test conditions	Min.	Typ.	Max.	Unit
P_{OUT}	$V_{DD}=7.5\text{V}$, $I_{DQ}=50\text{mA}$, $f=500\text{MHz}$	3		-	W
G_P	$V_{DD}=7.5\text{V}$, $I_{DQ}=50\text{mA}$, $P_{OUT}=3\text{W}$, $f=500\text{MHz}$	16	20	-	dB
r_P	$V_{DD}=7.5\text{V}$, $I_{DQ}=50\text{mA}$, $P_{OUT}=3\text{W}$, $f=500\text{MHz}$	50	55	-	%
Load mismatch	$V_{DD}=9.5\text{V}$, $I_{DQ}=50\text{mA}$, $P_{OUT}=3\text{W}$, $f=500\text{MHz}$ All phase angles	20:1		-	VSWR

Table 6. ESD protection characteristics

Test conditions	Class
Human body model	2
Machine model	M3

Table 7. Moisture sensitivity level

Test methodology	Rating
J-STD-020B	MSL 3

3 Typical performances

Figure 2. Capacitance vs supply voltage

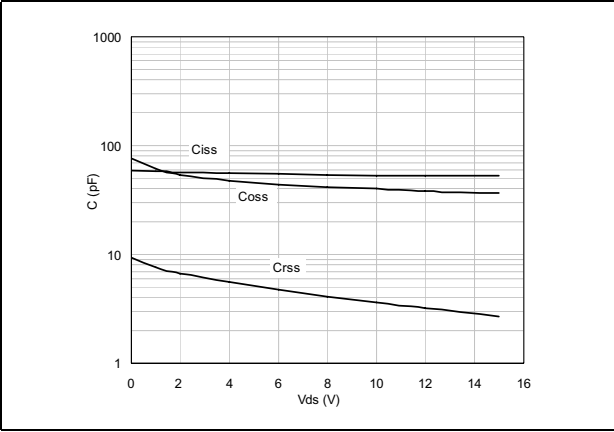


Figure 3. Output power vs input power

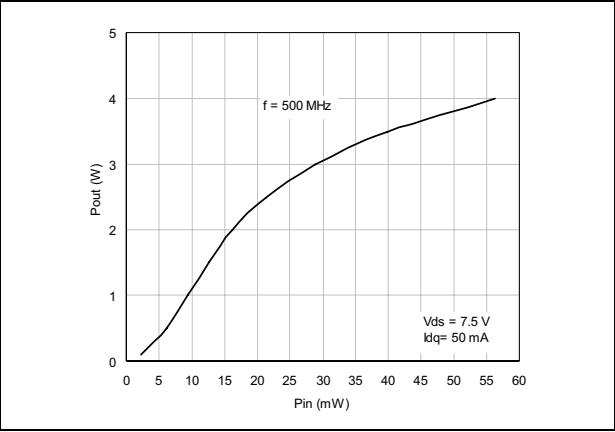


Figure 4. Power gain vs output power

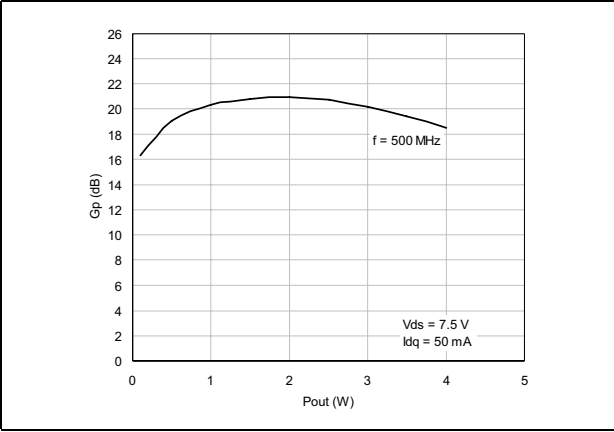


Figure 5. Efficiency vs output power

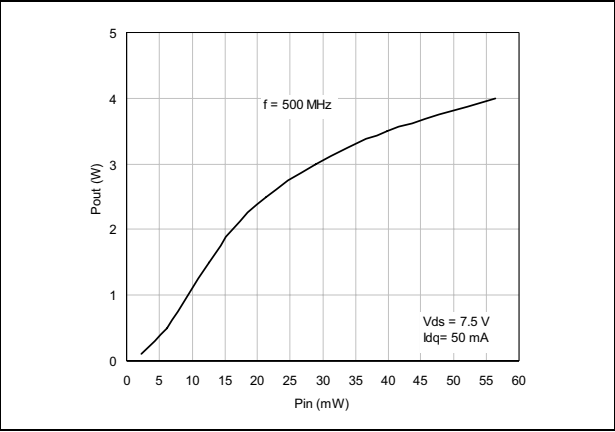


Figure 6. Output power vs bias current

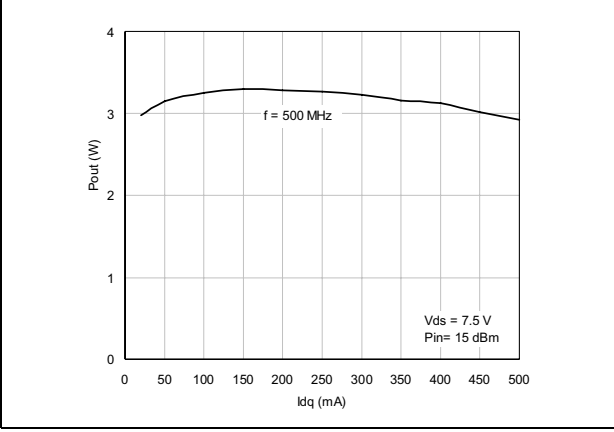


Figure 7. Output power vs gate-source voltage

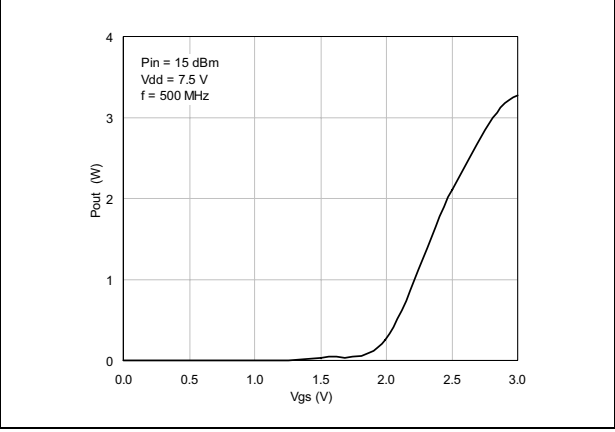


Figure 8. Efficiency vs bias current

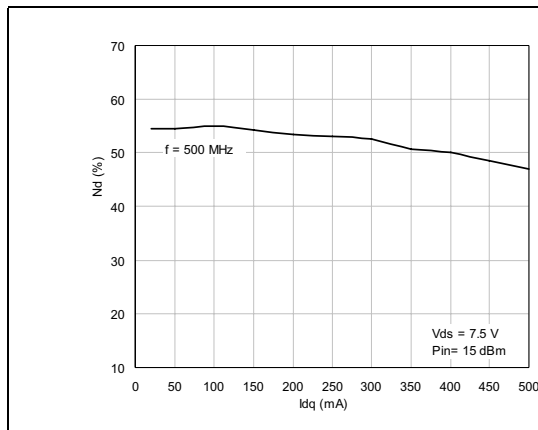
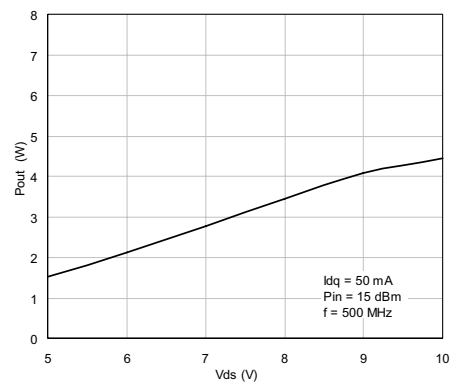


Figure 9. Output power vs supply voltage



3.1 Typical performance (broadband)

Figure 10. Power gain vs frequency

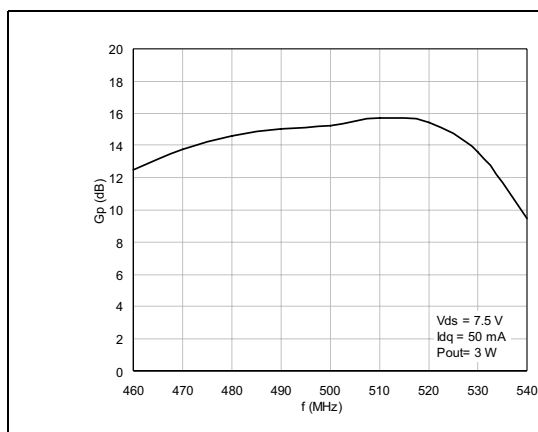


Figure 11. Efficiency vs frequency

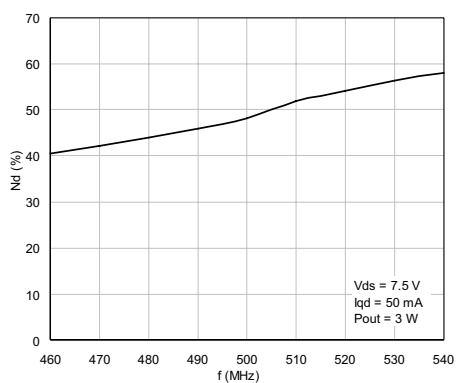
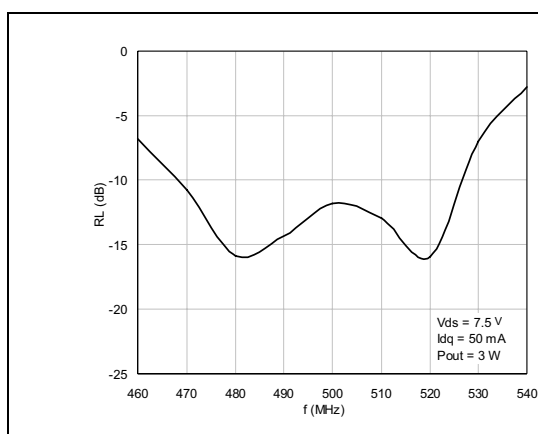


Figure 12. Return loss vs frequency



4 **Package mechanical data**

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. PowerFLAT™ mechanical data

Dim.	mm			inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A		0.90	1.00		0.035	0.039
A1		0.02	0.05		0.001	0.002
A3		0.24			0.009	
AA	0.15	0.25	0.35	0.006	0.01	0.014
b	0.43	0.51	0.58	0.017	0.020	0.023
c	0.64	0.71	0.79	0.025	0.028	0.031
D		5.00			0.197	
d		0.30			0.011	
E		5.00			0.197	
E2	2.49	2.57	2.64	0.098	0.101	0.104
e		1.27			0.050	
f		3.37			0.132	
g		0.74			0.03	
h		0.21			0.008	

Figure 13. PowerFLAT™ package dimensions

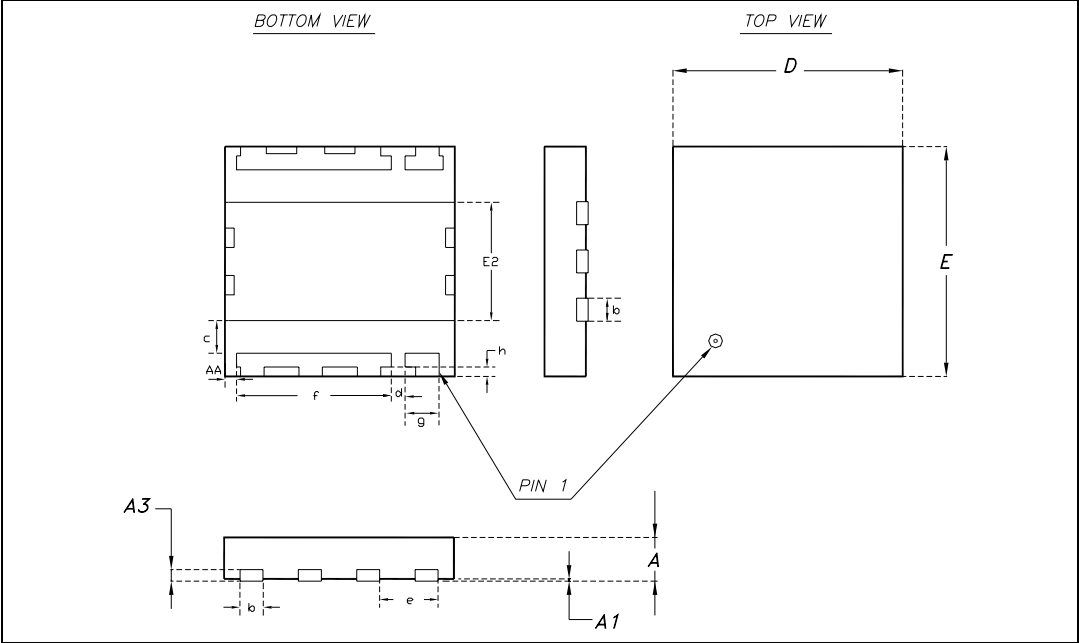


Table 9. PowerFLAT™ tape and reel dimensions

DIM.	mm.		
	Min.	Typ	Max.
Ao	5.15	5.25	5.35
Bo	5.15	5.25	5.35
Ko	1.0	1.1	1.2

Figure 14. PowerFLAT™ tape and reel

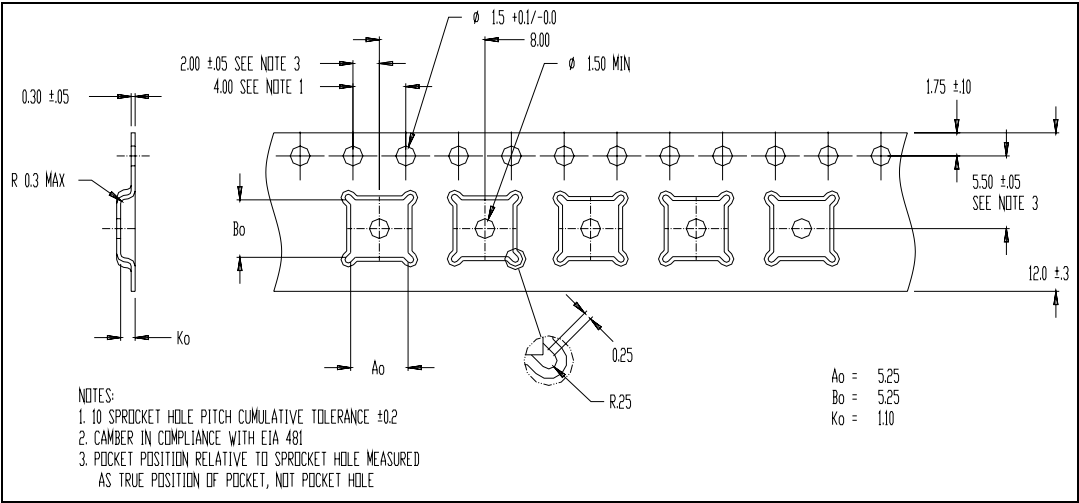
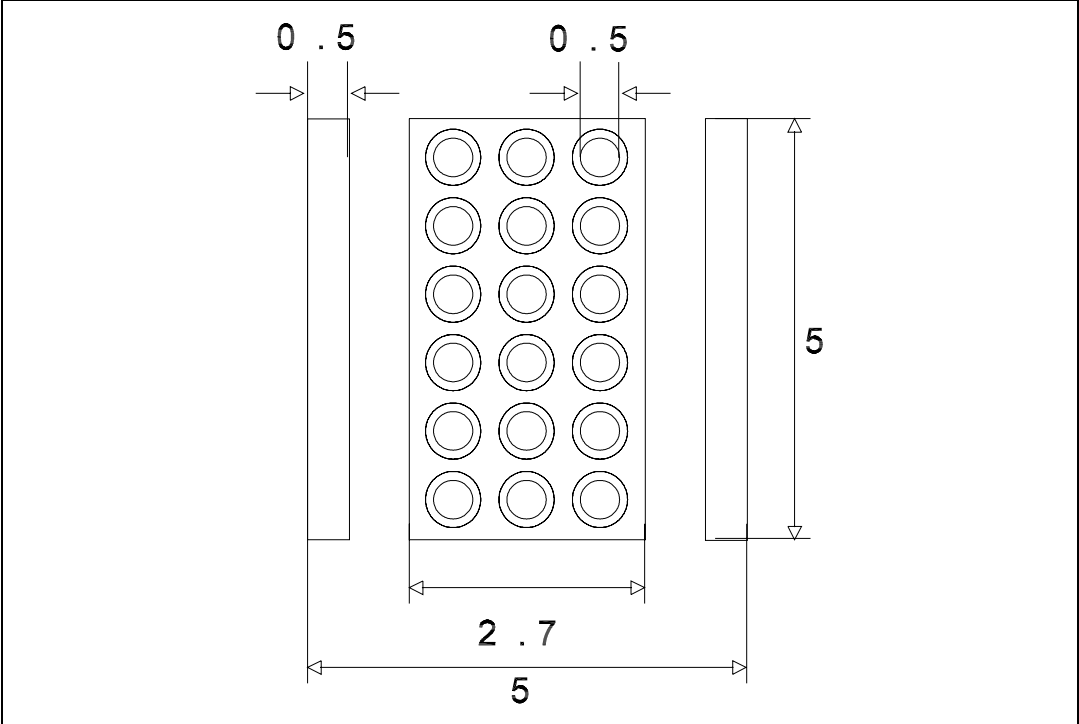


Figure 15. Recommended footprint



5 Revision history

Table 10. Document revision history

Date	Revision	Changes
04-Jan-2006	1	First Issue.
29-Apr-2011	2	Updated Table 4 .
10-May-2011	3	Updated Table 4 .

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